



## **TAOS Inc.**

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# ams AG

The technical content of this TAOS datasheet is still valid.

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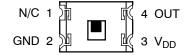
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- Converts Light Intensity to Output Voltage
- Monolithic Silicon IC Containing Photodiode, Transconductance Amplifier, and Feedback Components
- Single-Supply Operation . . . 2.7 V to 5.5 V
- High Irradiance Responsivity . . . Typical 96 mV/(μW/cm²) at λ<sub>p</sub> = 640 nm (TSL12T)
- Low Supply Current . . . 1.1 mA Typical
- Low-Profile Surface-Mount Package
- RoHS Compliant

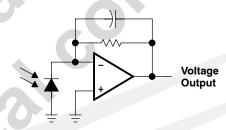
PACKAGE T 4-LEAD SMD (TOP VIEW)



#### Description

The TSL12T and TSL13T are cost-optimized, highly integrated light-to-voltage optical sensors, each combining a photodiode and a transimpedance amplifier (feedback resistor =  $80~\text{M}\Omega$  and  $20~\text{M}\Omega$ , respectively) on a single monolithic integrated circuit. The photodiode active area is  $0.5~\text{mm}\times0.5~\text{mm}$  and the sensors respond to light in the range of 320 nm to 1050 nm. Output voltage is linear with light intensity (irradiance) incident on the sensor over a wide dynamic range. These devices are supplied in a low-profile surface-mount package (T).

#### **Functional Block Diagram**



#### **Available Options**

DEV	ICE	T <sub>A</sub>	PACKAGE - LEADS	PACKAGE DESIGNATOR	ORDERING NUMBER
TSL	.12	0°C to 70°	4-lead Low-Profile Surface-Mount	\ T	TSL12T
TSL	.13	0°C to 70°	4-lead Low-Profile Surface-Mount	T	TSL13T

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### TSL12T, TSL13T LIGHT-TO-VOLTAGE CONVERTERS

TAOS062D - APRIL 2007

#### **Terminal Functions**

TERMINAL		
NAME	T PKG NO.	DESCRIPTION
GND	2	Power supply ground (substrate). All voltages are referenced to GND.
OUT	4	Output voltage.
$V_{DD}$	3	Supply voltage.
N/C	1	No connection.

#### Absolute Maximum Ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>DD</sub> (see Note 1)	
Output current, I <sub>O</sub>	±10 mA
Duration of short-circuit current at (or below) 25°C (see Note 2)	
Operating free-air temperature range, T <sub>A</sub>	-25°C to 85°C
Storage temperature range, T <sub>stg</sub>	-25°C to 85°C
Solder conditions in accordance with JEDEC J-STD-020A, maximum temperature	260°C

<sup>&</sup>lt;sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to GND.

2. Output may be shorted to supply.

#### **Recommended Operating Conditions**

		MIN	NOM MAX	UNIT
Supply voltage, V <sub>DD</sub>		2.7	5.5	V
Operating free-air temperature, T <sub>A</sub>	101	0	70	°C



# Electrical Characteristics at V<sub>DD</sub> = 5 V, T<sub>A</sub> = 25°C, $\lambda_p$ = 640 nm, R<sub>L</sub> = 10 k $\Omega$ (unless otherwise noted) (see Notes 3, 4, 5)

PARAMETER		TEST COMPLETIONS	TSL12T			TSL13T				
		TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
$V_{OM}$	Maximum output voltage		4.6	4.9		4.6	4.9		V	
		$E_e = 20.5 \mu W/cm^2$	1.5	2	2.5					
		$E_e = 83 \mu W/cm^2$				1.5	2	2.5	l	
Vo	Output voltage	$E_e = 41 \mu W/cm^2$	4			V				
		$E_e = 166 \mu\text{W/cm}^2$					4			
R <sub>e</sub>	Irradiance responsivity	Note 6		96			24		mV/ (μW/ cm <sup>2</sup> )	
Vos	Extrapolated offset voltage	Note 6	-0.02	0.03	0.08	-0.02	0.03	0.08	V	
V <sub>d</sub>	Dark voltage	E <sub>e</sub> = 0	0		0.08	0		0.08	V	
	0	$E_e = 20.5  \mu W/cm^2$		1.1	1.7				4	
I <sub>D</sub>	Supply current	$E_e = 83 \mu\text{W/cm}^2$					1.1	1.7	mA	

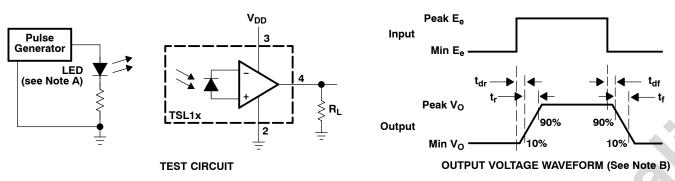
- NOTES: 3. Measurements are made with  $R_L$  = 10 k $\Omega$  between output and ground.
  - 4. Optical measurements are made using small-angle incident radiation from an LED optical source.
  - 5. The 640 nm input irradiance  $E_e$  is supplied by an AlInGaP LED with peak wavelength  $\lambda_p$  = 640 nm.
  - 6. Irradiance responsivity is characterized over the range  $V_O = 0.2$  to 4 V. The best-fit straight line of Output Voltage  $V_O$  versus irradiance  $E_e$  over this range may have a positive or negative extrapolated  $V_O$  value for  $E_e = 0$ . For low irradiance values, the output voltage  $V_O$  versus irradiance  $E_e$  characteristic is non linear with a deviation toward  $V_O = 0$ ,  $E_e = 0$  origin from the best-fit straight line referenced above.

# Dynamic Characteristics at V<sub>DD</sub> = 5 V, T<sub>A</sub> = 25°C, $\lambda_p$ = 640 nm, R<sub>L</sub> = 10 k $\Omega$ (unless otherwise noted) (see Figure 1)

DADAMETER		TEOT COMPLETIONS	TSL12T		•	TSL13T			
	PARAMETER	TEST CONDITIONS	MIN TY	P MAX	MIN	TYP	MAX	UNIT	
	Output pulse delay time for rising edge (0%	$Min V_O = 0 V; Peak V_O = 2 V$	13			1.7			
τ <sub>dr</sub>	to 10%)	$Min V_O = 0.5 V; Peak V_O = 2 V$	2	.3		1.2		μS	
Ī	0. 1. 1. 1. 1	$Min V_O = 0 V; Peak V_O = 2 V$	20			7.2		_	
τ <sub>r</sub>	Output pulse rise time (10% to 90%)	$Min V_O = 0.5 V; Peak V_O = 2 V$		0		6.5		μs	
Ī	Output pulse delay time for falling edge	Min $V_O = 0 V$ ; Peak $V_O = 2 V$	2	.3		1.2			
t <sub>df</sub>	100% to 90%)	Min $V_O = 0.5 \text{ V}$ ; Peak $V_O = 2 \text{ V}$	2	.2		1.1		μS	
	Output sules fall time (OOK) to 400()	Min $V_O = 0 V$ ; Peak $V_O = 2 V$		0		6.8			
τ <sub>f</sub>	Output pulse fall time (90% to 10%)	Min $V_O = 0.5 \text{ V}$ ; Peak $V_O = 2 \text{ V}$		9		6.4		μS	



#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input irradiance is supplied by a pulsed AlInGaP light-emitting diode with the following characteristics:  $\lambda_p$  = 640 nm,  $t_r < 1 \ \mu s$ .
  - B. The output waveform is monitored on an oscilloscope with the following characteristics:  $t_r < 100 \text{ ns}, Z_i \ge 1 \text{ M}\Omega, C_i \le 20 \text{ pF}.$

Figure 1. Switching Times

#### TYPICAL CHARACTERISTICS

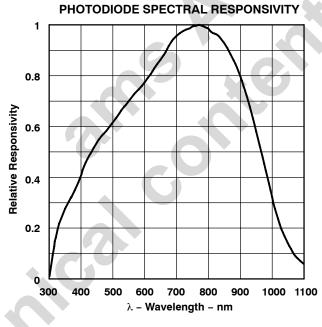
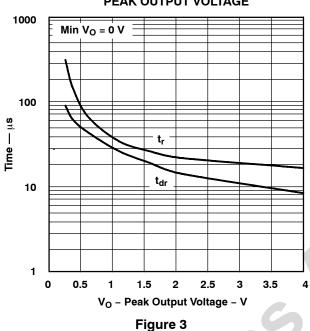


Figure 2

#### TSL12T

# RISING EDGE DYNAMIC CHARACTERISTICS

### PEAK OUTPUT VOLTAGE



# RISING EDGE DYNAMIC CHARACTERISTICS vs. PEAK OUTPUT VOLTAGE

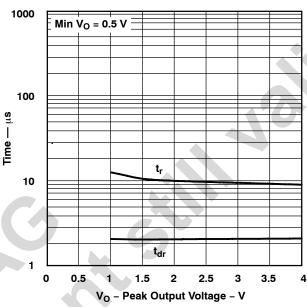
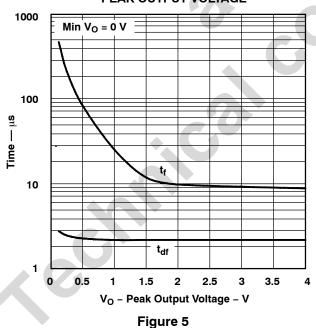


Figure 4

## FALLING EDGE DYNAMIC CHARACTERISTICS vs.

### PEAK OUTPUT VOLTAGE



# FALLING EDGE DYNAMIC CHARACTERISTICS vs.

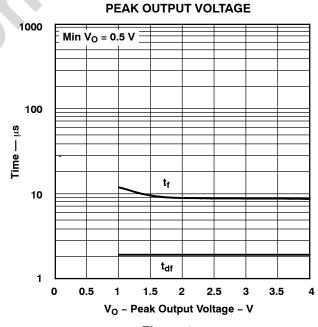


Figure 6



#### TSL12T

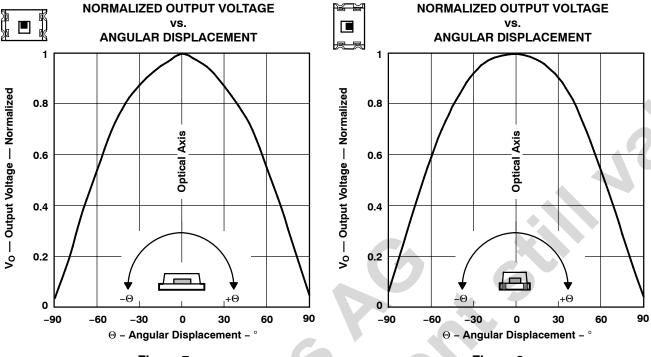
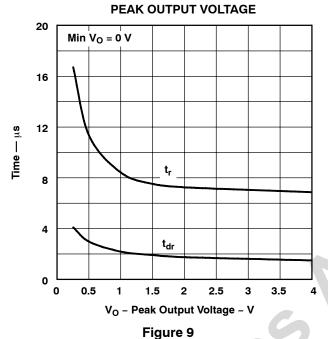


Figure 7

#### TSL13T

# RISING EDGE DYNAMIC CHARACTERISTICS vs.



# RISING EDGE DYNAMIC CHARACTERISTICS vs. PEAK OUTPUT VOLTAGE

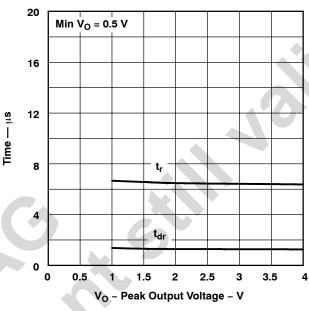
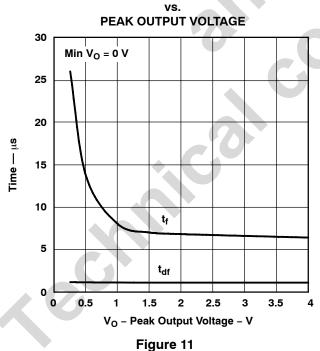


Figure 10

## FALLING EDGE DYNAMIC CHARACTERISTICS



# FALLING EDGE DYNAMIC CHARACTERISTICS vs.

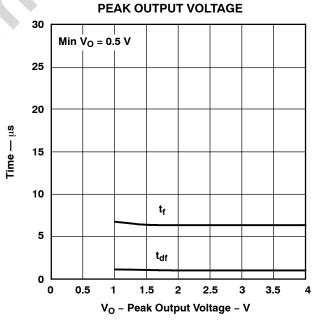
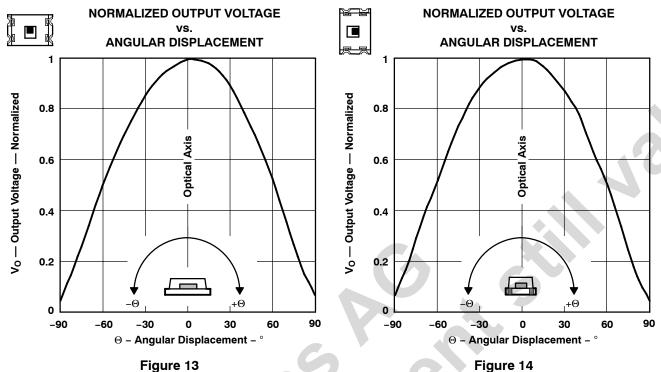


Figure 12



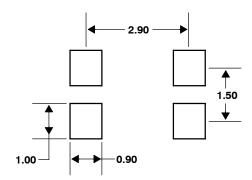
#### TSL13T



#### **APPLICATION INFORMATION**

### **PCB Pad Layout**

Suggested PCB pad layout guidelines for the T package are shown in Figure 15.



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

Figure 15. Suggested T Package PCB Layout

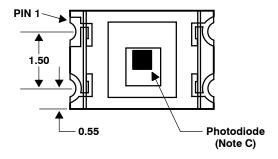
#### **MECHANICAL DATA**

The TSL12T and TSL13T are supplied in a low-profile surface-mount package. This package contains no lead (Pb).

#### **PACKAGE T**

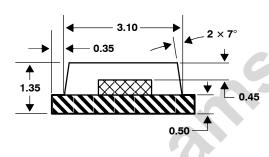
**Four-Lead Surface Mount Device** 

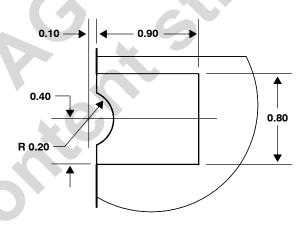
#### **TOP VIEW**



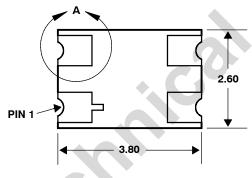
#### **DETAIL A: TYPICAL PACKAGE TERMINAL**

#### **SIDE VIEW**





#### **BOTTOM VIEW**





- NOTES: A. All linear dimensions are in millimeters.
  - B. Terminal finish is gold.
  - C. The center of the  $0.50 \text{ mm} \times 0.50 \text{ mm}$  integrated photodiode active area is typically located in the center of the package.
  - D. Dimension tolerance is ± 0.15 mm.
  - E. This drawing is subject to change without notice.

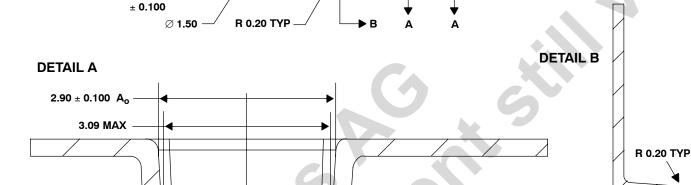
Figure 16. Package T — Four-Lead Surface Mount Device Packaging Configuration

#### $0.30 \pm 0.050$ 2.10 **SIDE VIEW** 1.75 ± 0.100 $4 \pm 0.100$ Ø 1.50 **END VIEW** $2 \pm 0.100$ 8 Тур 0 **TOP VIEW** $12 \pm 0.100$

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**MECHANICAL DATA** 



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**R 0.20 TYP** 

4.29 MAX  $4.10 \pm 0.100$  B<sub>0</sub> 1.80 K<sub>o</sub>

NOTES: A. All linear dimensions are in millimeters.

5.50

- B. The dimensions on this drawing are for illustrative purposes only. Dimensions of an actual carrier may vary slightly.
- C. Symbols on drawing A<sub>o</sub>, B<sub>o</sub>, and K<sub>o</sub> are defined in ANSI EIA Standard 481-B 2001.
- D. Each reel is 178 millimeters in diameter and contains 1000 parts.
- E. TAOS packaging tape and reel conform to the requirements of EIA Standard 481-B.
- In accordance with EIA standard, device pin 1 is located next to the sprocket holes in the tape.
- This drawing is subject to change without notice.

Figure 17. Four Lead Surface Mount Package Carrier Tape



#### **MANUFACTURING INFORMATION**

The reflow profile specified here describes expected maximum heat exposure of devices during the solder reflow process of the device on a PWB. Temperature is measured at the top of the device. Devices should be limited to one pass through the solder reflow profile.

Table 1. TSL12T, TSL13T Solder Reflow Profi	Table 1	. TSL12T.	TSL13T	Solder	Reflow	Profil
---	---------	-----------	--------	--------	--------	--------

PARAMETER	REFERENCE	TSL12T, TSL13T
Average temperature gradient in preheating		2.5°C/sec
Soak time	t <sub>soak</sub>	2 to 3 minutes
Time above T <sub>1</sub> , 217°C	t <sub>1</sub>	Max 60 sec
Time above T <sub>2</sub> , 230°C	t <sub>2</sub>	Max 50 sec
Time above T <sub>3</sub> , (T <sub>peak</sub> -10°C)	t <sub>3</sub>	Max 10 sec
Peak temperature in reflow	T <sub>peak</sub>	260° C (-0°C/+5°C)
Temperature gradient in cooling		Max -5°C/sec

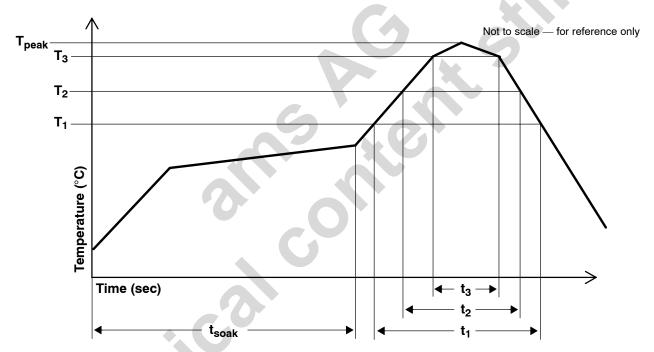


Figure 18. TSL12T, TSL13T Solder Reflow Profile

#### MANUFACTURING INFORMATION

#### **Moisture Sensitivity**

Optical characteristics of the device can be adversely affected during the soldering process by the release and vaporization of moisture that has been previously absorbed into the package molding compound. To ensure the package molding compound contains the smallest amount of absorbed moisture possible, each device is dry–baked prior to being packed for shipping. Devices are packed in a sealed aluminized envelope with silicagel to protect them from ambient moisture during shipping, handling, and storage before use.

This package has been assigned a moisture sensitivity level of MSL 3 and the devices should be stored under the following conditions:

Temperature Range 5°C to 50°C Relative Humidity 60% maximum

Total Time 6 months from the date code on the aluminized envelope — if unopened

Opened Time 168 hours or fewer

Rebaking will be required if the devices have been stored unopened for more than 6 months or if the aluminized envelope has been open for more than 168 hours. If rebaking is required, it should be done at 90°C for 4 hours.



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